Unit in mm

Field Effect Transistor Silicon N Channel MOS Type (L²-π-MOS III) High Speed, High Current DC-DC Converter, **Relay Drive and Motor Drive Applications**

Features

- 4-Volt Gate Drive
- Low Drain-Source ON Resistance
- $R_{DS(ON)} = 0.12\Omega$ (Typ.)
- High Forward Transfer Admittance
 - $|Y_{fs}| = 3.5S$ (Typ.)
- Low Leakage Current
- I_{GSS} = ±5μA (Max.) @ V_{GS} = ±16V I_{DSS} = 100μA (Max.) @ V_{DS} = 60V Enhancement-Mode
- - $V_{th} = -0.8 \sim 2.0 V @ V_{DS} = 10 V$, $I_D = 1 mA$

Absolute Maximum Ratings (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT		
Drain-Source Voltage		V _{DSS}	60	٧		
Drain-Gate Voltage ($R_{GS} = 20k\Omega$)		V _{DGR}	60	٧		
Gate-Source Voltage		V _{GSS}	±20	٧		
Drain Current	DC	I _D	5	Α		
	Pulse	I _{DP}	20			
Drain Power Dissipation (Tc = 25°C)		P _D	20	W		
Channel Temperature		T _{ch}	150	°C		
Storage Temperature Range		T _{stg}	-55 ~ 150	°C		

Thermal Characteristics

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	R _{th(ch-c)}	6.25	°C/W
Thermal Resistance, Channel to Ambient	R _{th(ch-a)}	125	°C/W

This transistor is an electrostatic sensitive device. Please handle with care.

6.8 MAX 5.2 ± 0.2 0.6MAX. GATE 2. DRAIN (HEAT SINK) 3. SOURCE

SC-64

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Industrial Applications

Weight: 0.36g

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Electrical Characteristics (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Current		I _{GSS}	$V_{GS} = \pm 16V, V_{DS} = 0V$	-	-	±5	μA
Drain Cut-off Current		I _{DSS}	$V_{DS} = 60V, V_{GS} = 0V$	-	_	100	μA
Drain-Source B	reakdown Voltage	V _{(BR) DSS}	I _D = 10mA, V _{GS} = 0V	60	_	-	٧
Gate Threshold	Voltage	V _{th}	V _{DS} = 10V, I _D = 1mA	0.8	_	2.0	٧
ON State Drain	Current	I _D (ON)	V _{DS} = 4V, V _{GS} = 4A	2.5	-	_	Α
Drain-Source ON Resistance		R _{DS (ON)}	$V_{GS} = 4V, I_D = 1.3A$	-	0.20	0.30	Ω
			V _{GS} = 10V, I _D = 2.5A	-	0.12	0.16	
Forward Transfe	er Admittance	Y _{fs}	$V_{DS} = 10V, I_D = 2.5A$	2.0	3.5	-	S
Input Capacitance		C _{iss}	V _{DS} = 10V, V _{GS} = 0V, f = 1MHz	-	380	530	pF
Reverse Transfer Capacitance		C _{rss}		-	95	150	
Output Capacitance		Coss		-	280	400	
	Rise Time	ŀ,	V _{GS 0V} I _{D=2.5A} V _{OUT} R _L = 12Ω	-	12	30	
Switching	Turn-on Time	ton		-	20	40	
Time	Fall Time	t _i			50	100	ns
ī	Turn-off Time	t _{off}		_	140	280	
			$V_{\text{IN}}: t_{\text{r}}, t_{\text{f}} < 5\text{ns}, V_{\text{DD}} = 30V$ $Duty \leq 1\%, t_{\text{w}} = 10\mu\text{s}$				
Total Gate Charge (Gate-Source Plus Gate-Drain) Gate-Source Charge		Qg	V _{DD} = 48V, V _{GS} = 10V,	-	20	40	_
		Q _{gs}	I _D = 5A	-	12	-	nC
Gate-Drain ("M	iller") Charge	Q _{gd}		-	8	_	1

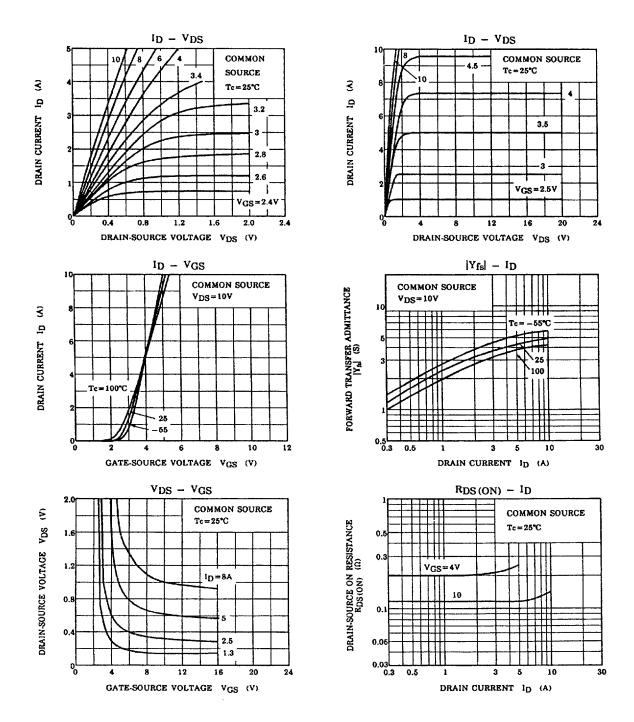
Source-Drain Diode Ratings and Characteristics (Ta = 25°C)

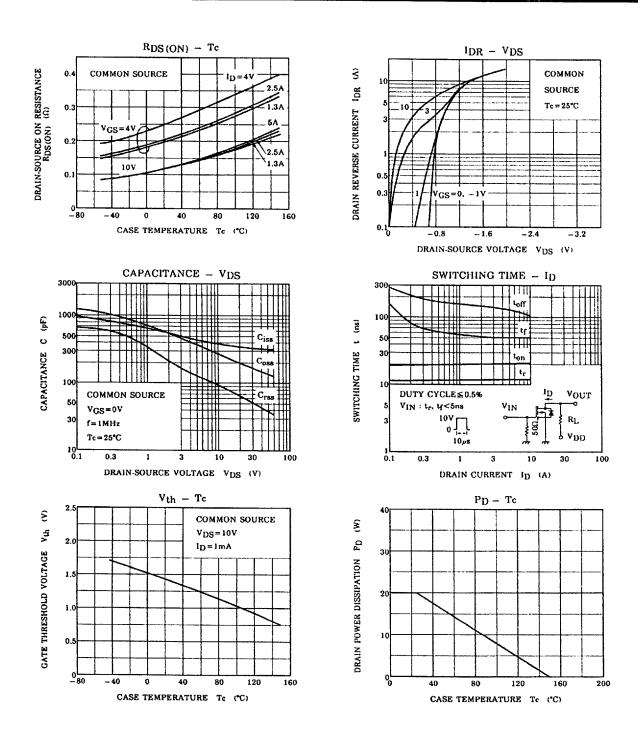
CHARACTERISTICS	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	I _{DR}	-	_	_	5	A
Pulse Drain Reverse Current	I _{DRP}	-	-		20	Α
Diode Forward Voltage	V _{DSF}	I _{DR} = 5A, V _{GS} = 0V		-1.0	-1.7	٧
Reverse Recovery Time	t _{rr}	I _{DR} = 5A, V _{GS} = 0V		120	_	ns
Reverse Recovered Charge	Q _{rr}	dl _{DR} /dt = 20A/µs	<u> </u>	0.09	_	μC

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